

# Our team

InSCOPE, the Pilot line is serviced by top European RTD's with leading technological positions and state of the art equipment in the domain of Printed electronics.



## InSCOPE figures

- 9.2 M€ budget
  - (EU contribution 8.0 M€)
- 716 Person Months
- 11 partners from 8 countries
- 4 high value added showcases
  - (large enterprise industry targeting)
- 16 SME development cases
- Executive advisory board (EAB) throughout the whole value chain
- Start date January 1st, 2017 (3 years)



## RE-IMAGINE THE FUTURE OF ELECTRONICS



## INDUSTRY REQUESTS



FLEXIBLE



STRETCHABLE



3D



READY  
FOR PRODUCTION



# Re-imagine the future of electronics

## About the InSCOPE project

The project, titled InSCOPE, aims to create impact by offering a pilot line service that advances accuracy and reliability of hybrid printed electronics. It allows faster transition of the product concept from R&D to product and supports the build of manufacturing capacity will also give a great chance for SMEs to enter the market with Thin, Organic and Large Area Electronics enabled products.



## VISION

To become the leading Hybrid Printed electronics development service worldwide that create sufficient market traction to allow self-sustaining operation.

## MISSION

To provide a comprehensive complementary toolbox for Hybrid Printed Electronics manufacturing processes. Demonstrate the commercial viability- present 4 Showcases that will show Hybrid Printed electronics capabilities in large volume markets. Set up service infrastructure for hybrid Printed Electronics enable a service of 15 development cases during the project.

## Our Capabilities

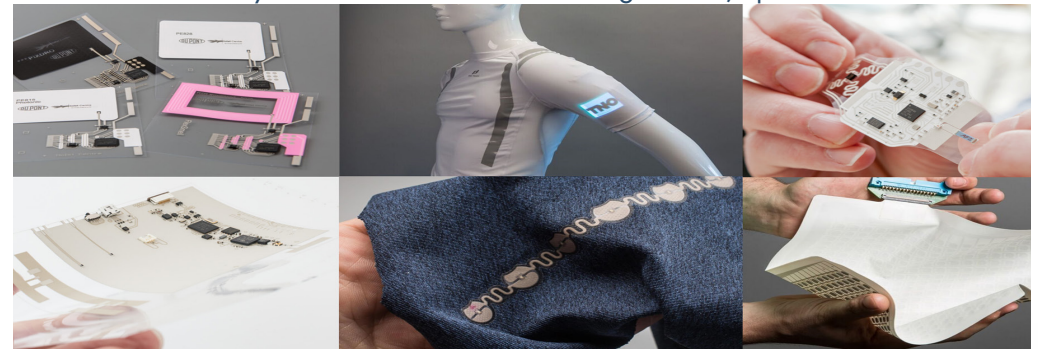
The pilot line is modular, ensuring a comprehensive toolbox of printing, assembly, production integration and process validation distributed over the InSCOPE partners.

# Potential of printed electronics

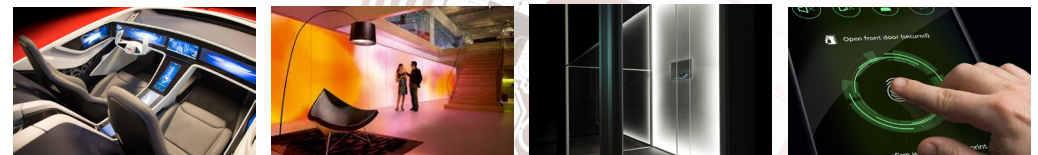
Printed electronics is the technology to construct functional electronics on foil using conventional print technologies combined with traditional pick and place assembly techniques and is addressed as an emerging technology with high growth potential.

## Well suited

The technology is especially suited for market sectors that require high standards and quality products combined with unique (smart) functionalities- require flexibility or even stretchability and that are available in large areas/quantities.



Examples can be found in the automotive, health, smart packaging and smart buildings sectors.



## OUTCOME

The goal is to transform smarter: Brought by European leading research institutes within the InSCOPE project that enables its users to replace PCB (printed circuit boards) with printed circuits on foil. Printed electronics replace the rigid conventional circuit boards by conformable foils. This way electronics can be transferred into 3D shaped products and at the same time be manufactured on a large scale, and ultimately on a roll-to-roll basis.